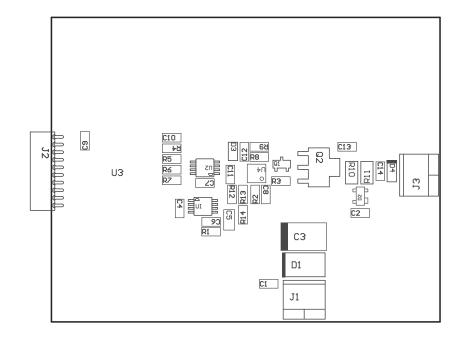
ZZ1 These assemblies are ESD sensitive, ESD precautions shall be observed.

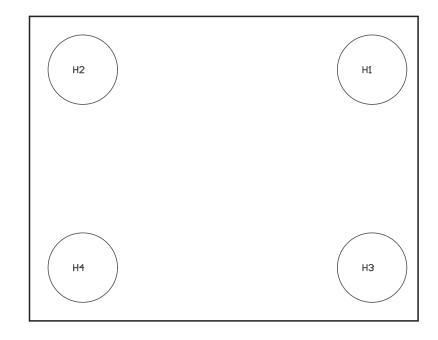
ZZ2 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01536	REV: A	SVN REV: Not In VersionControl		
	TID #: TIDA-01536				
PLOT NAME = Top Assembly Drawing	GENERATED : 7/28/2	2017 1:10:46	PM TEXAS INSTRU	MENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01536 REV: A	SVN REV: Not In VersionControl		
	TID #: TIDA-01536			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/28/2017 1:10:47	PM TEXAS INSTRUMENTS		

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